

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jing-En Luan	09/07/2010
RECEIVING PARTY DATA	
Name:	STMicroelectronics Asia Pacific PTE Ltd.
Street Address:	5A Serangoon North Avenue 5
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	554574
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12893651
CORRESPONDENCE DATA	
Fax Number:	(206)682-6031
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	206.622.4900
Email:	kristines@seedip.com
Correspondent Name:	Hayley J. Stevens
Address Line 1:	701 Fifth Avenue
Address Line 2:	Suite 5400
Address Line 4:	Seattle, WASHINGTON 98104
ATTORNEY DOCKET NUMBER:	851663.502
NAME OF SUBMITTER:	Hayley J. Stevens
Total Attachments: 2 source=502_Assignment#page1.tif source=502_Assignment#page2.tif	

CH \$40.00 12893651

501305506

PATENT
REEL: 025063 FRAME: 0361

ASSIGNMENT

WHEREAS, I, Jing-En Luan (hereinafter referred to as ASSIGNOR), having a mailing address of BLK 538, #02-4014 Ang Mo Kio Avenue, Singapore, Singapore 560538, am the sole inventor of an invention entitled "WAFER LEVEL PACKAGING METHOD USING COMPOSITE MATERIAL AS A BASE," as described and claimed in the specification for which an application for United States letters patent was filed on September 29, 2010 and assigned Application No. 12/893,651;

WHEREAS, STMicroelectronics Asia Pacific PTE Ltd. (hereinafter referred to as ASSIGNEE), a corporation of the Country of Singapore having a place of business at 5A Serangoon North Avenue 5, Singapore, Singapore 554574, is desirous of acquiring from us our entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR hereby sells, assigns and transfers unto said ASSIGNEE the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions including any extensions or adjustments in term thereof and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR had this assignment, transfer and sale not been made. ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR agrees to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefor.



Application No. 12/893,651

Assignee's counsel is authorized to insert the official filing date and application number information when it becomes available.

07/09/2010
Date


Jing-En Luan

(851663.502 / 1665609_1.DOC)